

### Lead (Pb) Free Product - RoHS Compliant







#### Feature

- · P-LCC-2 package.
- Colorless clear resin.
- Wide viewing angle 120°.
- Inner reflector and white package.
- Brightness: 180 to 355 mcd at 20mA.
- Precondition: Bases on JEDEC J-STD 020D Level 3.
- Qualification according to AEC-Q101 rev C.
- Automotive reflow profile (IR reflow or wave soldering)

## **Applications**

- Automotive backlighting or indicator: Interior and exterior lighting, Dashboard, switch, reading lamp, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- Optical indicator.
- General applications.

#### **Device Selection Guide**

Chip	Emitted Color	Resin Color	
Material	Emitted Color		
AlGaInP	Brilliant Yellow	Water Clear	



# Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	$V_R$	12	V
Forward Current	$I_{\mathrm{F}}$	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	$I_{\mathrm{FP}}$	100	mA
Power Dissipation	Pd	120	mW
Junction Temperature	$T_{\rm j}$	125	$^{\circ}\!\mathbb{C}$
Operating Temperature	$T_{opr}$	-40 ~ +100	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{\mathrm{stg}}$	-40 ~ +110	$^{\circ}\!\mathbb{C}$
	Rth <sub>J-A</sub>	500	K/W
Thermal resistance	Rth <sub>J-S</sub>	300	K/W
ESD	ESD <sub>HBM</sub>	2000	V
(Classification acc. AEC Q101)	ESD <sub>MM</sub>	200	V
Soldering Temperature	$T_{sol}$	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	



## Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	Iv	180		355	mcd	I <sub>F</sub> =20mA
Viewing Angle	$2\theta_{1/2}$		120		deg	I <sub>F</sub> =20mA
Peak Wavelength	λр		591		nm	I <sub>F</sub> =20mA
Dominant Wavelength	λd	583		589	nm	I <sub>F</sub> =20mA
Spectrum Radiation Bandwidth	Δλ		15		nm	I <sub>F</sub> =20mA
Forward Voltage	$V_{\mathrm{F}}$	1.7		2.4	V	I <sub>F</sub> =20mA
Reverse Current	$I_R$			10	μА	$V_R = 12V$
Temperature coefficient of λp	$TC_{\lambda p}$		0.06		nm/K	I <sub>F</sub> =20mA
Temperature coefficient of λd	$TC_{\lambda d}$		0.4		nm/K	I <sub>F</sub> =20mA
Temperature coefficient of V <sub>F</sub>	$TC_V$		-2.3		mV/K	I <sub>F</sub> =20mA

#### Note:

1. Tolerance of Luminous Intensity:  $\pm 11\%$ 

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage:  $\pm 0.1V$ 



## **Bin Range of Luminous Intensity**

Bin Code	Min.	Max.	Unit	Condition
S1	180	224		
S2	224	280	mcd	$I_F = 20 \text{mA}$
T1	280	355		

Notes: Tolerance of Luminous Intensity: ±11%

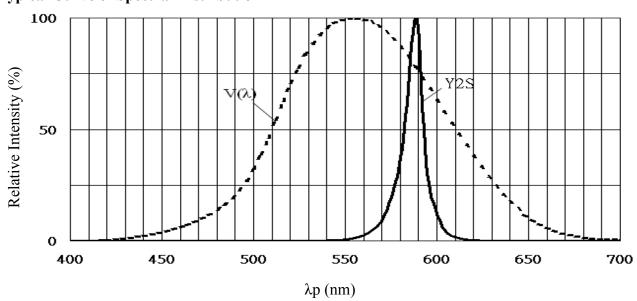
## **Bin Range of Dominant Wavelength**

Bin Code	Min.	Max.	Unit	Condition
1	583	586		I <sub>F</sub> =20mA
2	586	589	nm	

Notes: Tolerance of Dominant Wavelength: ±1nm

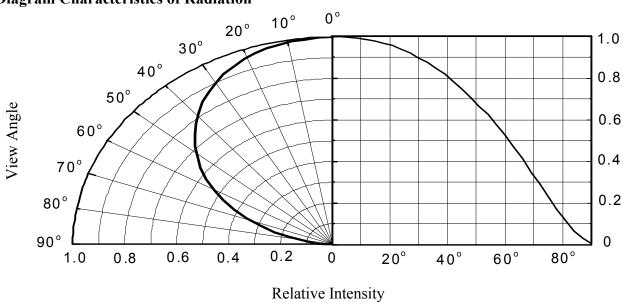


# **Typical Electro-Optical Characteristics Curves Typical Curve of Spectral Distribution**



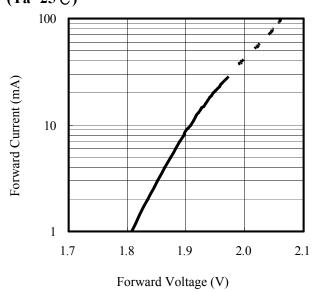
Note:  $V(\lambda)$ =Standard eye response curve

## **Diagram Characteristics of Radiation**

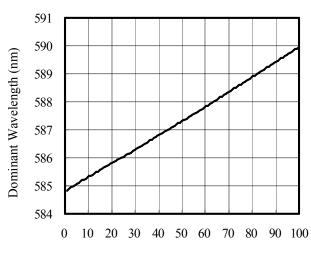




# Forward Current vs. Forward Voltage (Ta=25°C)

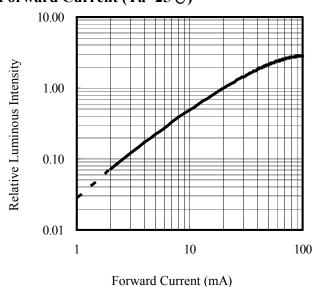


# **Dominant Wavelength vs. Forward Current** (Ta=25°C)

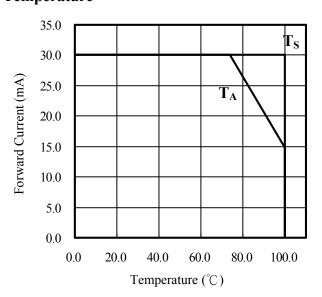


Forward Current (mA)

# Relative Luminous Intensity vs. Forward Current (Ta=25°C)



# Forward current vs. Ambient and Solder Temperature



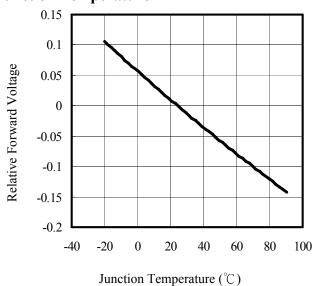


# Relative Luminous Intensity vs. Junction Temperature

### 1.40 1.20 Relative Luminous Intensity 1.00 0.80 0.60 0.40 0.20 0.00 -40 -20 40 80 100 20 Junction Temperature (°C)

Note:  $f(Tj) = Iv / Iv(25^{\circ}C)$ ;  $I_F = 20mA$ 

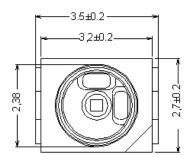
# Relative Forward Voltage vs. Junction Temperature

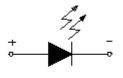


Note:  $\triangle V_F = V_F - V_F(25 \degree C) = f(Tj)$ ;  $I_F = 20 \text{mA}$ 



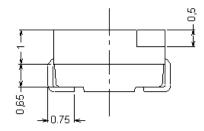
# **Package Dimension**

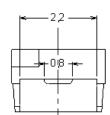




Polarity

## Chip position

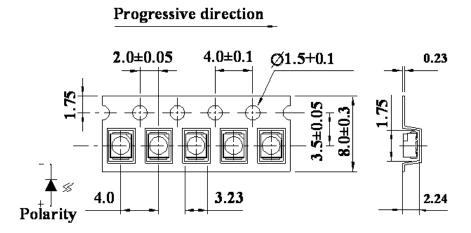




Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm



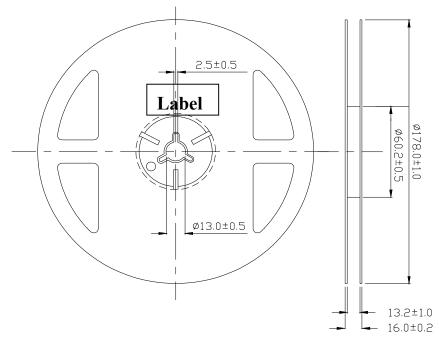
## Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

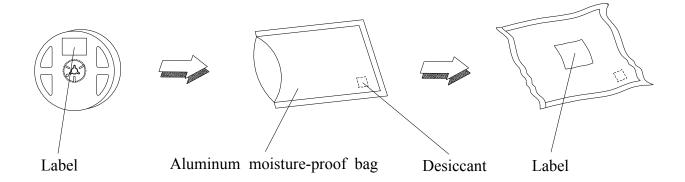


## **Reel Dimensions**



Note: Unit = mm

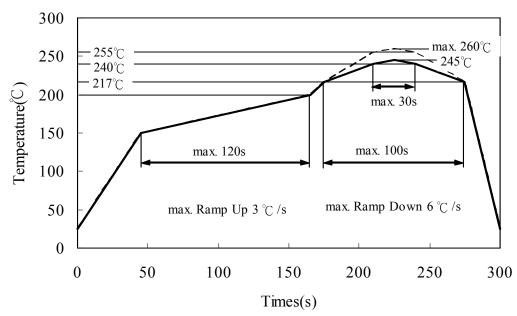
## **Moisture Resistant Packing Process**



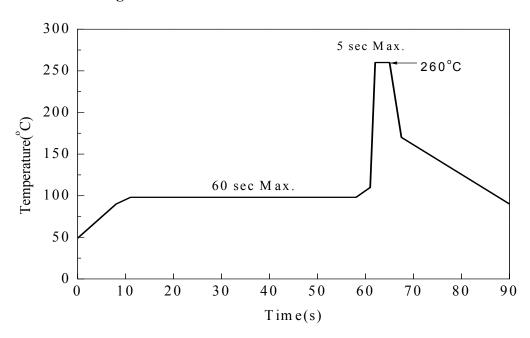


### **Precautions for Use**

- 1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)
  - a. IR reflow

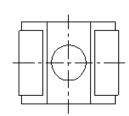


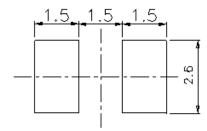
### b. Wave soldering reflow





#### (B) Recommend soldering pad





Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

#### 2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

#### 3. Storage

- 3.1 Moisture proof bag should only be opened immediately prior to usage.
- 3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.
- 3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

#### 4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

#### 5. Usage

Do not exceed the values given in this specification.

### **Application Restrictions**

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.